



VMDSEMI

VFPA010R250NA

Datasheet



VMDSEMI

General Description

Symbol

$V_{(BR)DSS}$	$R_{DS(ON)_{max}}$	I_D
100V	25mΩ@10V	35A
	33mΩ@4.5V	

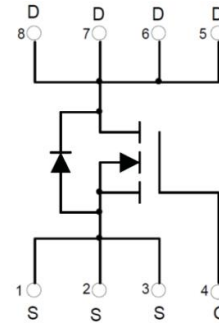


Figure 1 Symbol of VFPA010R250NA

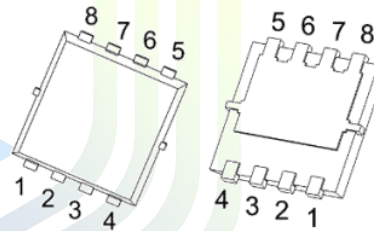
Features

- Split Gate Trench Technology
- Low $R_{DS(ON)}$
- Low Gate Charge
- Low Gate Resistance
- 100% UIS Tested

Application

- Industrial Power Supply
- Load Switch

Package Type



PDFN3.3X3.3-8L

Figure 2 Package Type of VFPA010R250NA

Ordering Information

Product Name	Package
VFPA010R250NA	PDFN3.3X3.3 -8L

Absolute Maximum Ratings ($T_A = 25\text{ °C}$, unless otherwise specified)

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V_{DSS}	100	V
Gate-Source Voltage	V_{GSS}	± 20	V
Continuous Drain Current ^{Note1}	I_D	35	A
Pulsed Drain Current ^{Note2}	I_{DM}	140	
Avalanche Current ^{Note3}	I_{AS}	12	
Single Pulsed Avalanche Energy ^{Note3}	E_{AS}	7.2	mJ
Total Power Dissipation ^{Note5}	P_D	30	W
Junction Temperature	T_J	150	°C
Storage Temperature	T_{STG}	-55 to 150	°C

Thermal Resistance

Parameter	Symbol	Min	Typ	Max	Unit
Thermal Resistance, Junction-to-Ambient ^{Note6}	$R_{\theta JA}$	-	55	-	°C/W
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	-	4.2	-	°C/W



Electrical Characteristics ($T_J = 25^\circ\text{C}$, unless otherwise specified)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Statistic Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0V, I_D=250\mu A$	100	-	-	V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=100V, V_{GS}=0V$	-	-	1	μA
Gate-Body Leakage Current	I_{GSS}	$V_{GS} = \pm 20V, V_{DS}=0V$	-	-	± 100	nA
Gate Threshold Voltage ^{Note4}	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	1	1.5	3	V
Static Drain-Source On-Resistance ^{Note4}	$R_{DS(on)}$	$V_{GS}=10V, I_D=20A$	-	19	25	mΩ
		$V_{GS}=4.5V, I_D=15A$	-	25	33	
Forward Transconductance ^{Note4}	g_{FS}	$V_{DS}=5V, I_D=20A$	-	53	-	S
Dynamic Characteristics						
Input Capacitance	C_{ISS}	$V_{DS}=45V$	-	781	-	pF
Output Capacitance	C_{OSS}	$V_{GS}=0V$	-	277.3	-	pF
Reverse Transfer Capacitance	C_{RSS}	$f=1MHz$	-	14.1	-	pF
Total Gate Charge	Q_g	$V_{DS}=50V$	-	14.6	-	nC
Gate-Source Charge	Q_{gs}	$V_{GS}=10V$	-	1.3	-	
Gate-Drain Charge	Q_{gd}	$I_D=20A$	-	4.3	-	
Gate Resistance	R_g	$f=1MHz, \text{Open drain}$	-	2.0	-	Ω
Switching Parameters						
Turn-on Delay Time	$t_{d(on)}$	$V_{DD}=50V$	-	7.5	-	ns
Turn-on Rise Time	t_r	$V_{GS}=10V$	-	3.5	-	
Turn-off Delay Time	$t_{d(off)}$	$R_L=2.5\Omega$	-	23	-	
Turn-off Fall Time	t_f	$R_G=3.0\Omega$	-	4.5	-	
Diode Characteristics						
Diode Forward Voltage ^{Note4}	V_{SD}	$V_{GS}=0V, I_S=10A$	0.5	-	1.2	V

Notes :

1. The maximum current rating is limited by package. And device mounted on a large heatsink.
2. Pulse Test : Pulse Width $\leq 10\mu s$, duty cycle $\leq 1\%$.
3. EAS condition: $V_{DD} = 50V, V_{GS} = 10V, L = 0.1mH, R_G = 25\Omega$ Starting $T_J = 25^\circ C$.
4. Pulse Test : Pulse Width $\leq 300\mu s$, duty cycle $\leq 2\%$.
5. The power dissipation P_D is limited by $T_{J(MAX)} = 150^\circ C$. And device mounted on a large heatsink
6. Device mounted on $1in^2$ FR-4 board with 2oz. Copper, in a still air environment with $T_A = 25^\circ C$.

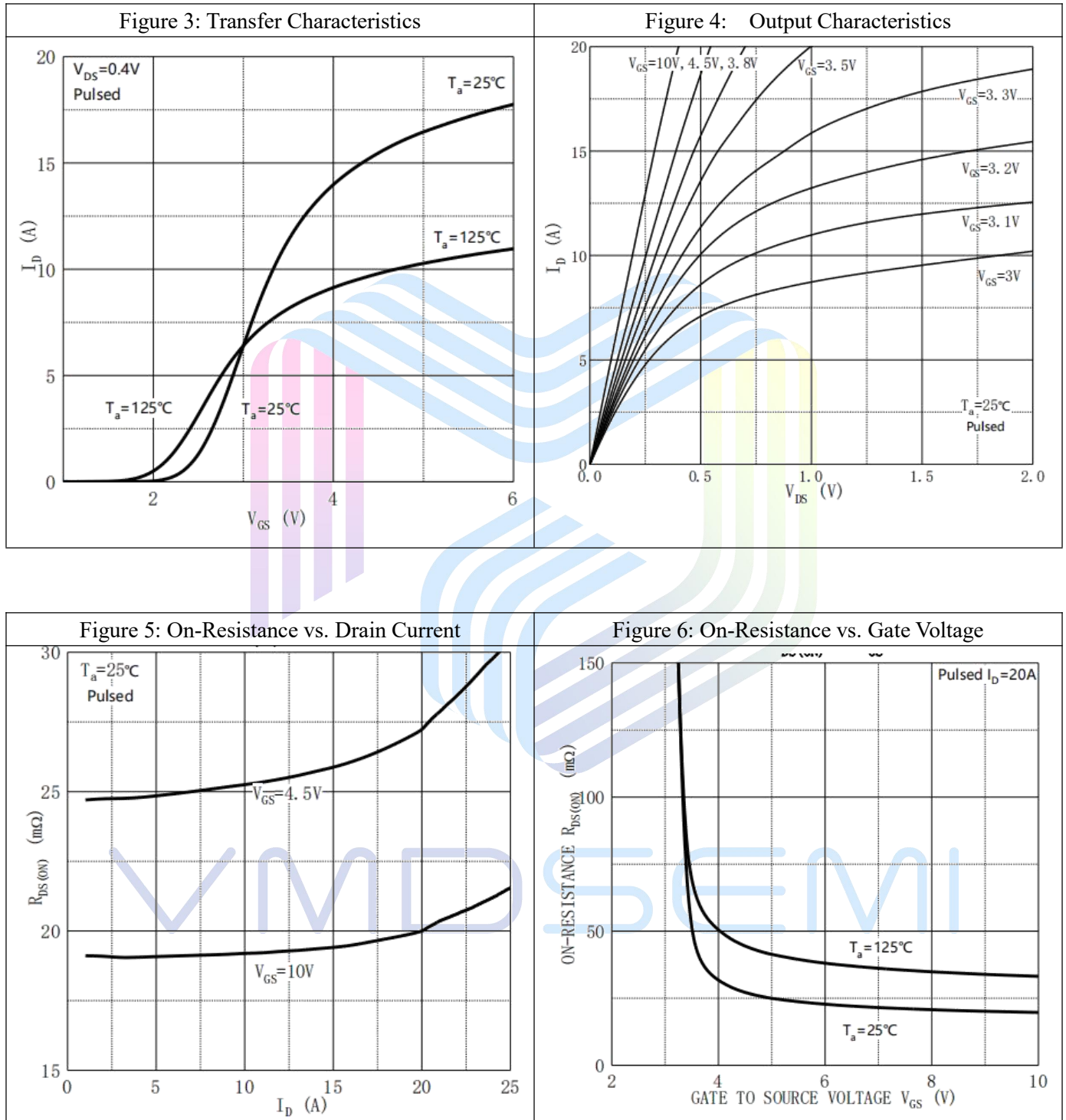
Typical Performance Characteristics


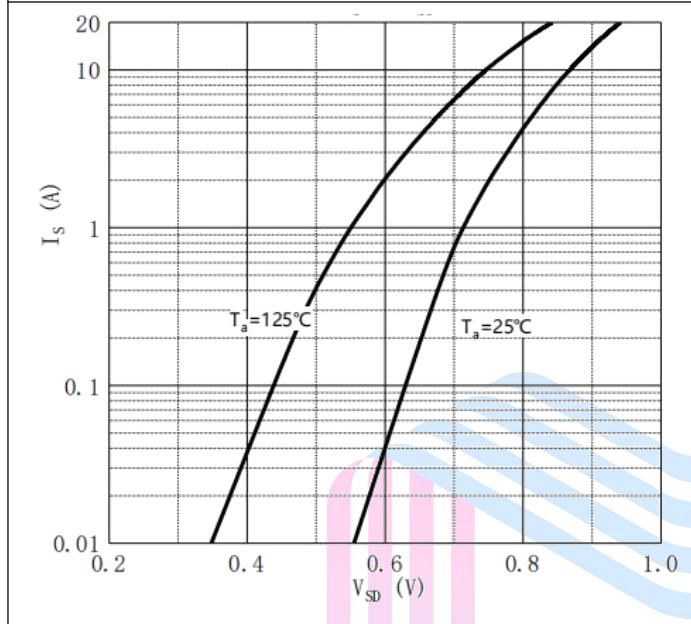
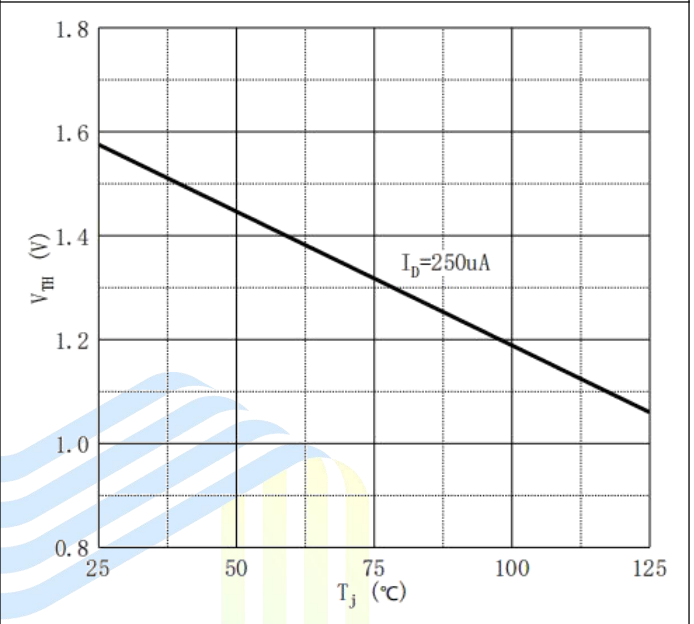
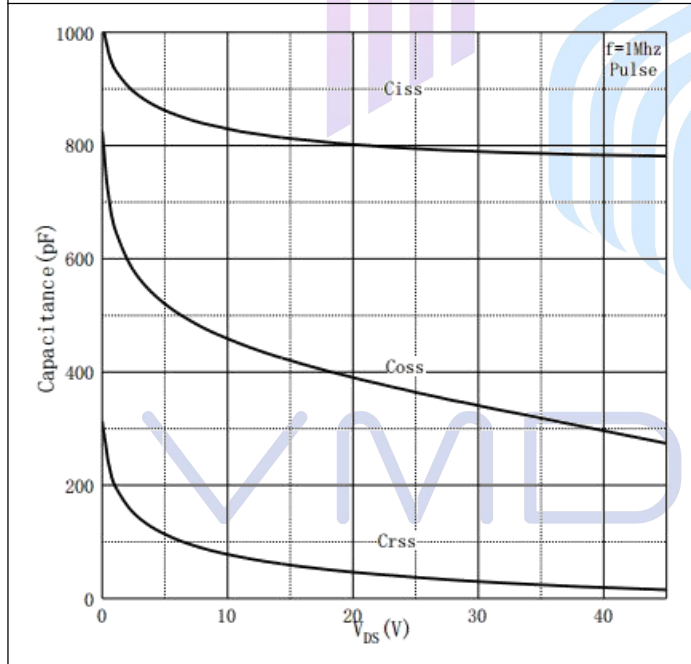
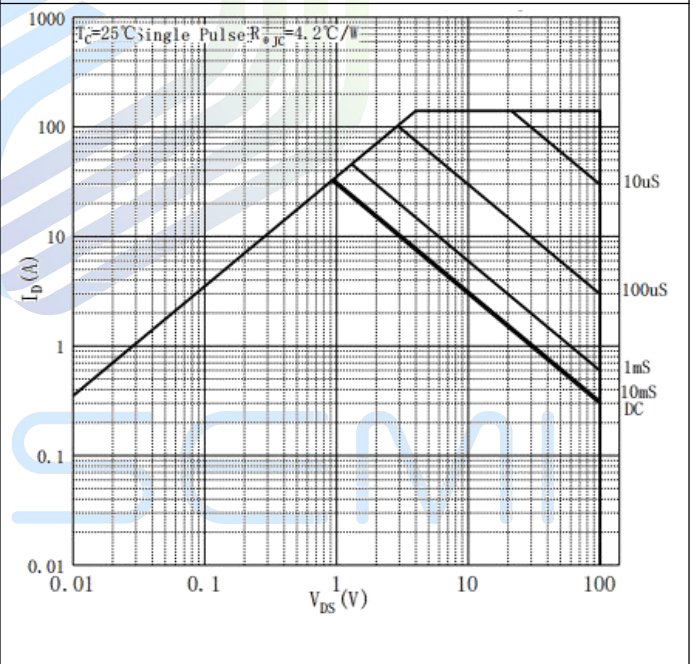
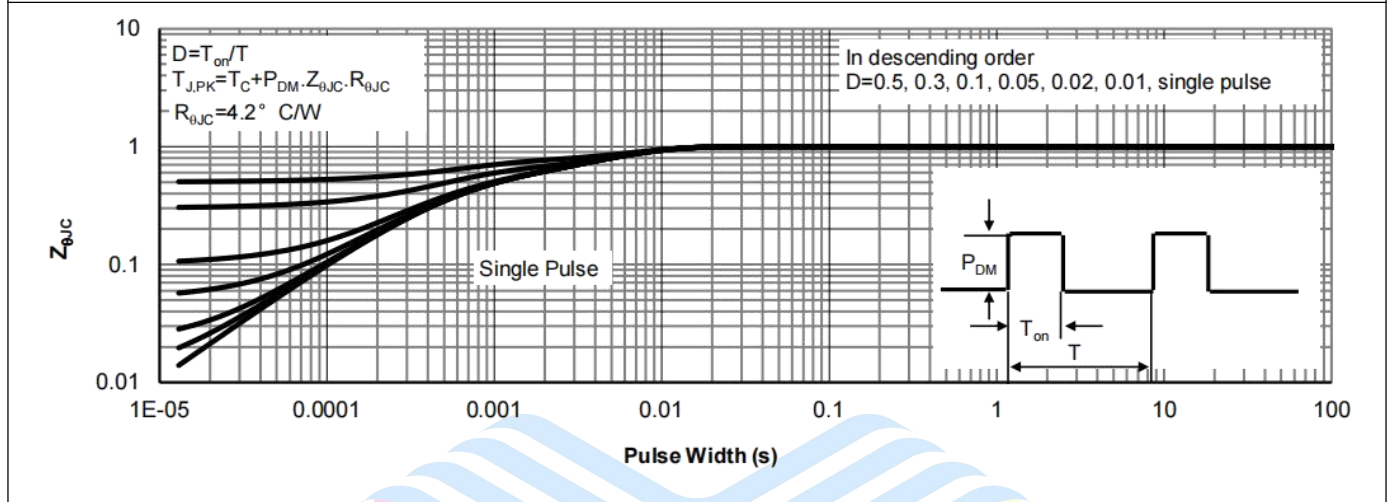
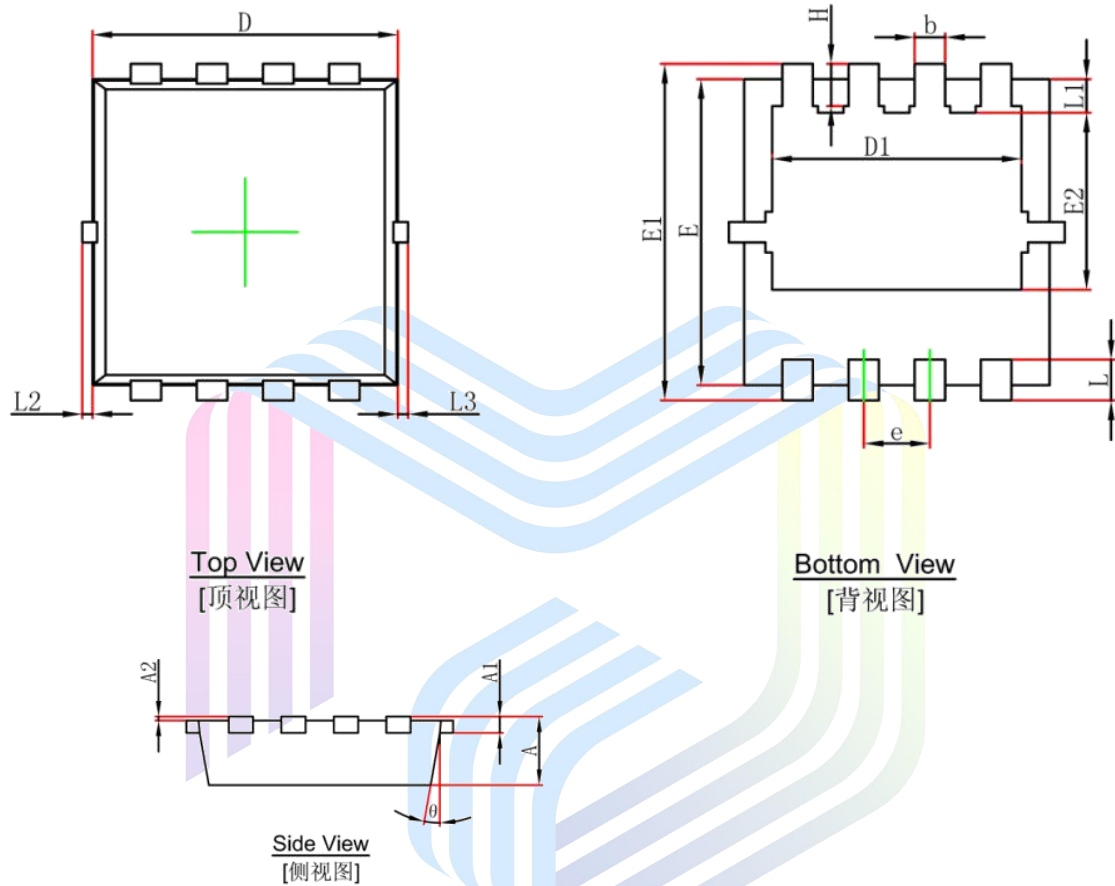
Figure 7: Body Diode Characteristics

Figure 8: Threshold Voltage

Figure 9: Typical Capacitance

Figure 10: Safe Operation Area


Figure 11: Normalized Maximum Transient Thermal Impedance



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Mechanical Dimensions:
PDFN3.3X3.3-8L Package Information


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.700	0.900	0.028	0.035
A1	0.152REF		0.006REF	
A2	0.000	0.050	0.000	0.002
D	2.900	3.200	0.114	0.126
D1	2.300	2.600	0.091	0.102
E	2.900	3.200	0.114	0.126
E1	3.150	3.450	0.124	0.136
E2	1.535	1.935	0.060	0.076
b	0.200	0.400	0.008	0.016
e	0.550	0.750	0.022	0.030
L	0.300	0.500	0.012	0.020
L1	0.180	0.480	0.007	0.019
L2	0.000	0.100	0.000	0.004
L3	0.000	0.100	0.000	0.004
H	0.315	0.515	0.012	0.020
θ	0°	12°	0°	12°

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